

MOSFETs Silicon P-Channel MOS (U-MOSVI)

TJ30S06M3L

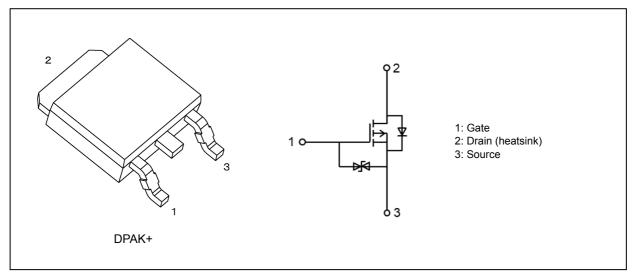
1. Applications

- Automotive
- · Motor Drivers
- · DC-DC Converters
- Switching Voltage Regulators

2. Features

- (1) AEC-Q101 qualified
- (2) Low drain-source on-resistance: $R_{DS(ON)} = 16.8 \text{ m}\Omega$ (typ.) ($V_{GS} = -10 \text{ V}$)
- (3) Low leakage current: $I_{DSS} = -10 \mu A \text{ (max) (V}_{DS} = -60 \text{ V)}$
- (4) Enhancement mode: V_{th} = -2.0 to -3.0 V (V_{DS} = -10 V, I_D = -1 mA)

3. Packaging and Internal Circuit





4. Absolute Maximum Ratings (Note) (Ta = 25°C unless otherwise specified)

Characteristics			Rating	Unit
Drain-source voltage		V_{DSS}	-60	V
Gate-source voltage		V _{GSS}	-20/+10	
Drain current (DC)	(Note 1)	I _D	-30	Α
Drain current (pulsed)	(Note 1)	I _{DP}	-60	
Power dissipation (T _c	= 25°C)	P _D	68	W
Single-pulse avalanche energy	(Note 2)	E _{AS}	71	mJ
Avalanche current		I _{AR}	-30	Α
Channel temperature	(Note 3)	T _{ch}	175	°C
Storage temperature	(Note 3)	T _{stg}	-55 to 175	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

5. Thermal Characteristics

Characteristics		Max	Unit
Channel-to-case thermal resistance	R _{th(ch-c)}	2.2	°C/W

Note 1: Ensure that the channel temperature does not exceed 175°C.

Note 2: V_{DD} = -25 V, T_{ch} = 25°C (initial), L = 107 μ H, R_{G} = 25 Ω , I_{AR} = -30 A

Note 3: The definitions of the absolute maximum channel and storage temperatures are qualified per AEC-Q101.

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

2024-12-18



6. Electrical Characteristics

6.1. Static Characteristics (T_a = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	V _{GS} = -16/+10 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-off current	I _{DSS}	V _{DS} = -60 V, V _{GS} = 0 V	_	_	-10	
Drain-source breakdown voltage	V _{(BR)DSS}	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-60			V
Drain-source breakdown voltage (Note 4)	V _{(BR)DSX}	I _D = -10 mA, V _{GS} = 10 V	-50	_		
Gate threshold voltage	V_{th}	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$	-2.0	_	-3.0	
Drain-source on-resistance	R _{DS(ON)}	V _{GS} = -6 V, I _D = -15 A	_	19	28	mΩ
		V _{GS} = -10 V, I _D = -15 A	_	16.8	21.8	

Note 4: If a forward bias is applied between gate and source, this device enters $V_{(BR)DSX}$ mode. Note that the drain-source breakdown voltage is lowered in this mode.

6.2. Dynamic Characteristics (T_a = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz	_	3950	_	pF
Reverse transfer capacitance	C _{rss}		_	270	_	
Output capacitance	C _{oss}		_	360	_	
Switching time (rise time)	t _r	See Figure 6.2.1.	_	43	_	ns
Switching time (turn-on time)	t _{on}		_	64	_	
Switching time (fall time)	t _f		_	118	_	
Switching time (turn-off time)	t _{off}		_	430		

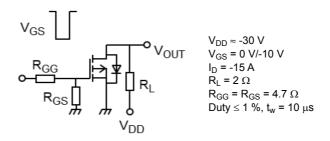


Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics (T_a = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Q_g	$V_{DD} \approx -48 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -30 \text{ A}$	_	80	_	nC
Gate-source charge	Q _{gs}		_	54	_	
Gate-drain charge	Q_{gd}		_	26	_	

6.4. Source-Drain Characteristics (T_a = 25°C unless otherwise specified)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (DC)	(Note 5)	I _{DR}	_	_	_	-30	Α
Reverse drain current (pulsed)	(Note 5)	I _{DRP}	_	_	_	-60	
Diode forward voltage		V _{DSF}	$I_{DR} = -30 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V
Reverse recovery time		t _{rr}	$I_{DR} = -30 \text{ A}, V_{GS} = 0 \text{ V}$	_	39	_	ns
Reverse recovery charge		Q _{rr}	dI _{DR} /dt = 50 A/μs	_	22	_	nC

Note 5: Ensure that the channel temperature does not exceed 175°C.

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7. Marking (Note)

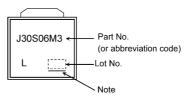


Fig. 7.1 Marking

Note: A line under a Lot No. identifies the indication of product Labels.

Not underlined: [[Pb]]/INCLUDES > MCV

Underlined: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]]

Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS

compatibility of Product.

The RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.



8. Characteristics Curves (Note)

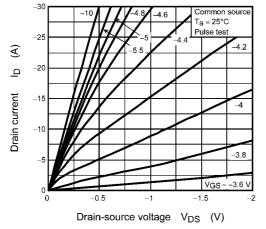
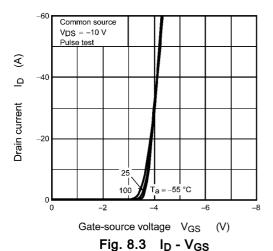


Fig. 8.1 I_D - V_{DS}



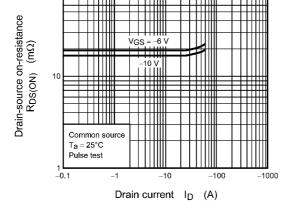


Fig. 8.5 R_{DS(ON)} - I_D

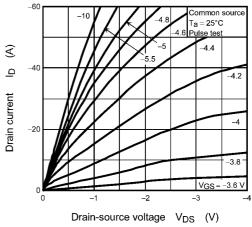


Fig. 8.2 I_D - V_{DS}

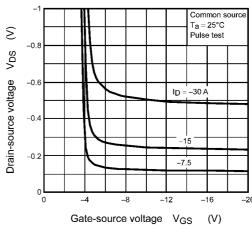


Fig. 8.4 V_{DS} - V_{GS}

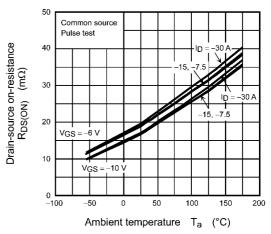


Fig. 8.6 R_{DS(ON)} - T_a



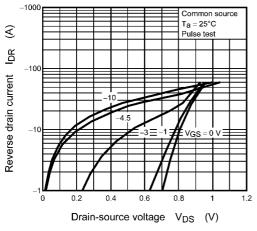


Fig. 8.7 IDR - VDS

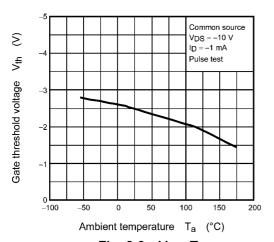


Fig. 8.9 V_{th} - T_a

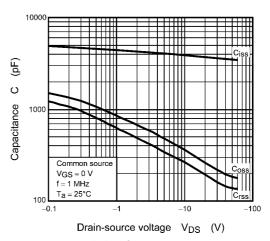


Fig. 8.8 Capacitance - V_{DS}

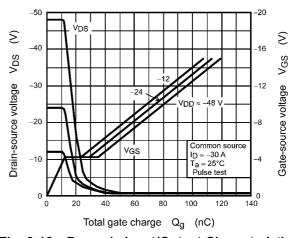


Fig. 8.10 Dynamic Input/Output Characteristics



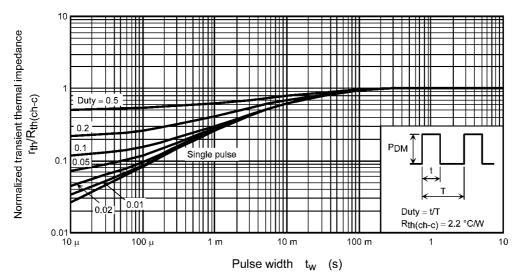


Fig. 8.11 $r_{th}/R_{th(ch-c)} - t_w$ (Guaranteed Maximum)

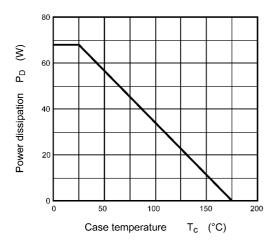


Fig. 8.12 P_D - T_c (Guaranteed Maximum)

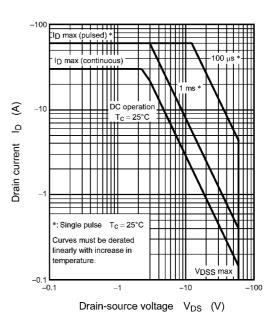


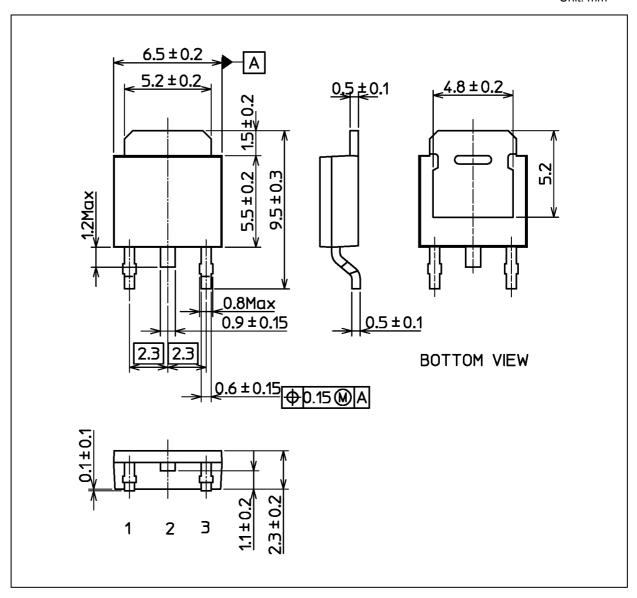
Fig. 8.13 Safe Operating Area (Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



Package Dimensions

Unit: mm



Weight: 0.36 g (typ.)

	Package Name(s)
TOSHIBA: 2-7M1A	
Nickname: DPAK+	



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